MSKSEMI















ESD

TVS

TSS

MOV

GDT

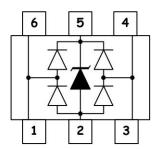
PLED

Broduct data sheet



SOT-23-6

Pin Configuration



Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 Air discharge: ±30kV

Contact discharge: ±25kV

- IEC61000-4-4 (EFT) 4.5A (5/50ns)
- RoHS Compliant

Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)

Mechanical Characteristics

• Package: SOT-23-6

• Lead Finish: Lead Free

• UL Flammability Classification Rating 94V-0

Quantity Per Reel:3,000pcs

Reel Size:7inch

Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|---------------------------------|------------------|-------------|---------------|
| Peak Pulse Power (8/20µs) | Ррр | 150 | W |
| ESD per IEC 61000-4-2 (Air) | \/ | ±20 | Kv |
| ESD per IEC 61000-4-2 (Contact) | V _{ESD} | ±15 | KV |
| Operating Temperature Range | TJ | -55 to +125 | $^{\circ}$ C |
| Storage Temperature Range | T _{STJ} | -55 to +150 | ${\mathbb C}$ |



Electrical Characteristics(TA=25°C unless otherwise specified)

| | | V_{RWM} | V _{BR} I _T | Ιτ | Ιτ | Vc | Iτ Vc | Vc | | I _R | C |
|-------------|---------|-----------|--------------------------------|-----|-------|------|-------------|----------------|-----|----------------|---|
| P/N Marking | Marking | (V) (V) | (mA) | @1A | (Max) | (@A) | μΑ (Max) | (Pf) (Typ.) | | | |
| USBLC6-2SC6 | UL26 | 5 | 6 | 1 | 9.8 | 15 | 4.5 | 1 | 0.3 | | |

Characteristic Curves

Fig1. $8/20\mu$ s Pulse Waveform

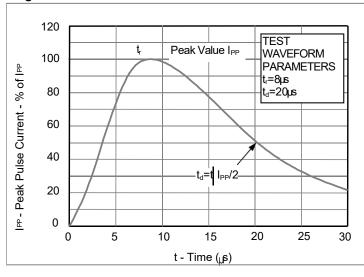


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

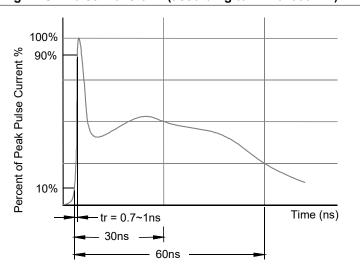
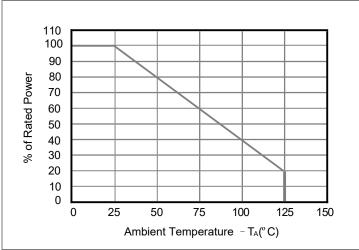


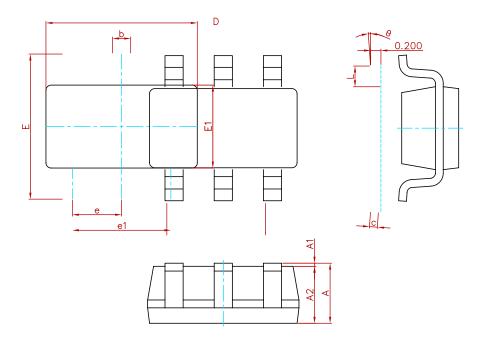
Fig3. Power Derating Curve





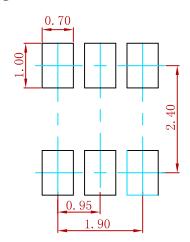
Semiconductor

PACKAGE MECHANICAL DATA



| Symbol | Dimensions In | n Millimeters | Dimensions In Inches | | |
|--------|---------------|---------------|----------------------|-------|--|
| Symbol | Min. | Max. | Min. | Max. | |
| Α | 1.050 | 1.250 | 0.041 | 0.049 | |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 1.050 | 1.150 | 0.041 | 0.045 | |
| b | 0.300 | 0.500 | 0.012 | 0.020 | |
| С | 0.100 | 0.200 | 0.004 | 0.008 | |
| D | 2.820 | 3.020 | 0.111 | 0.119 | |
| E1 | 1.500 | 1.700 | 0.059 | 0.067 | |
| Е | 2.650 | 2.950 | 0.104 | 0.116 | |
| е | 0.950(BSC) | | 0.037(BSC) | | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 | |
| L | 0.300 | 0.600 | 0.012 | 0.024 | |
| θ | 0° | 8° | 0° | 8° | |

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|-------------|----------|------|
| USBLC6-2SC6 | SOT-23-6 | 3000 |



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